JOCT147XH-W8

Rev.A.1.0

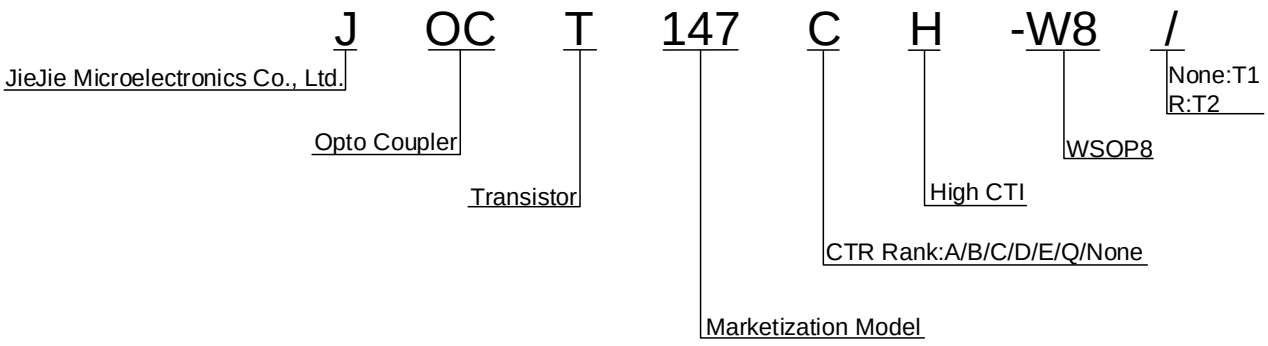
DESCRIPTION:

The products are transistor opto-couplers in a plastic WSOP8 package. The device which is infrared LED chip and photo-transistor chip is assemble

Unit
V
μA
-

CTR

ORDERING INFORMATION



Packing Quantity	
Option	**Quantity**

MARKING

Characteristics Curves

FIG.1: Max. Allowable LED Forward Current vs. Ambient Temperature

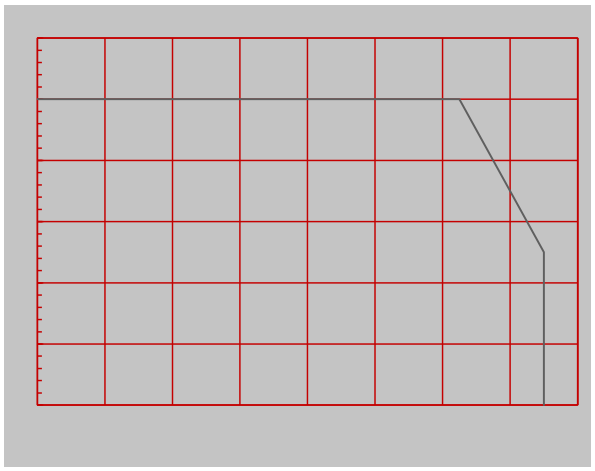


FIG.2: Collector Power Dissiption vs. Ambient Temperature

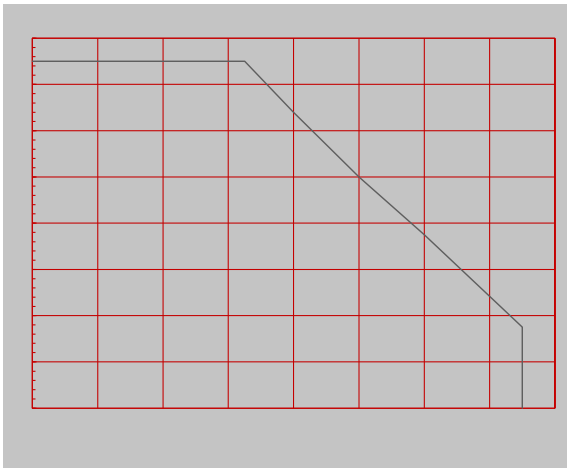


FIG.3: Forward Current vs. Forward Voltage

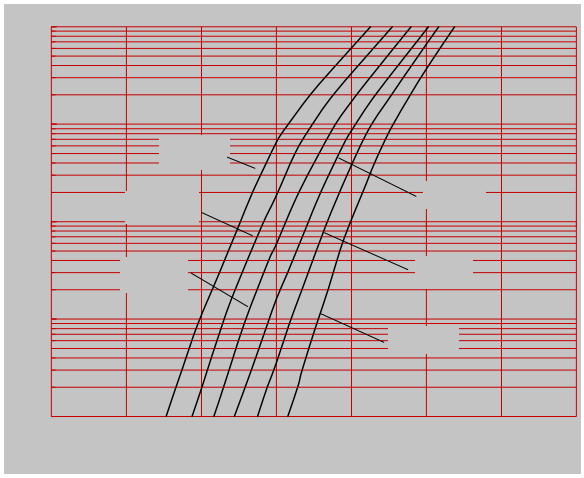


FIG.4: Collector Dark Current vs. Ambient Temperature

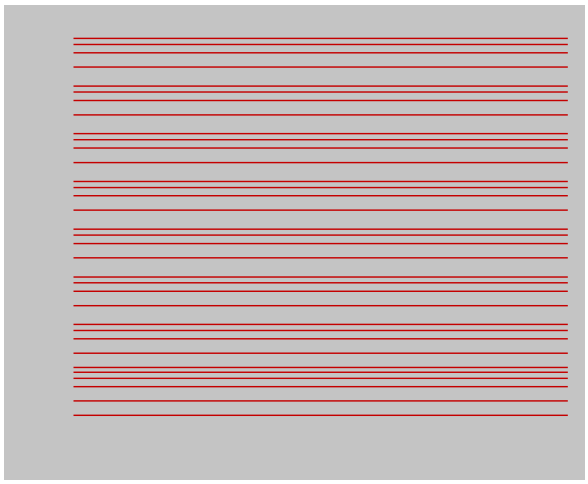


FIG.7: Current Transfer Ratio vs. Forward Current

FIG.8: Current Transfer Ratio vs. Ambient Temperature

Test Circuits

FIG.12: Test Circuits of Turn On Time

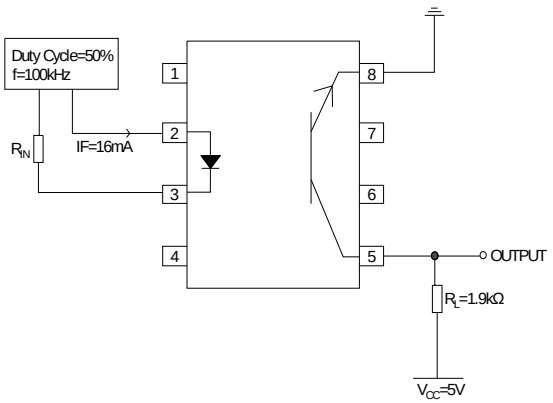
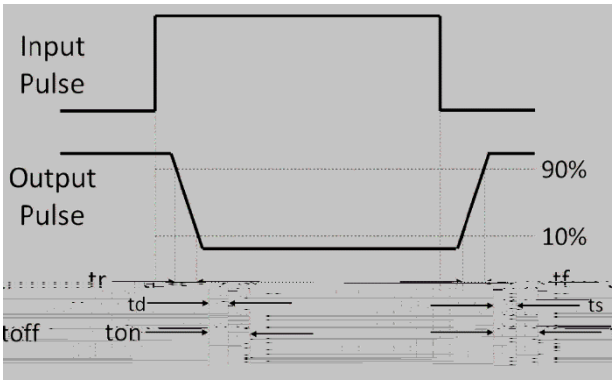
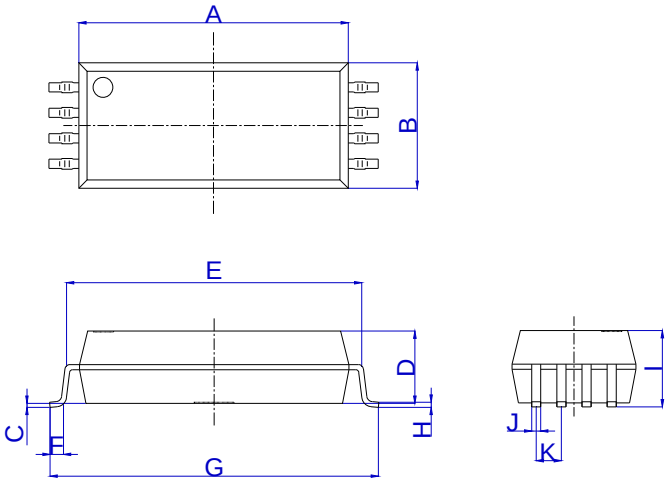


FIG.13: Waveforms of Turn On Time

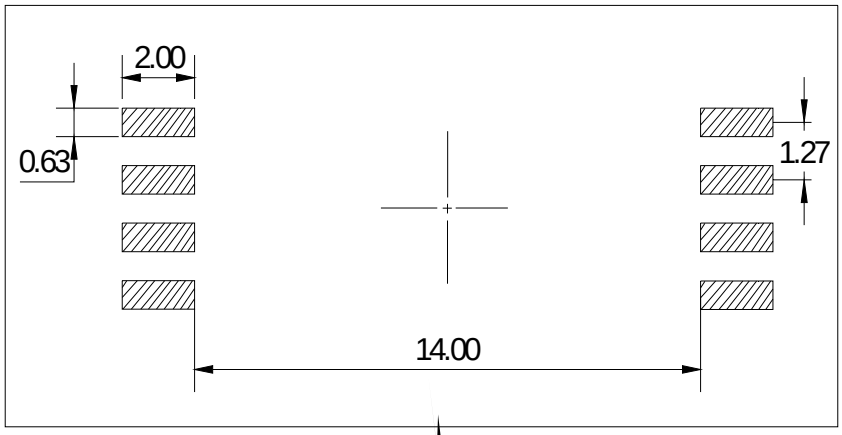


Package Dimension (Unit: mm)



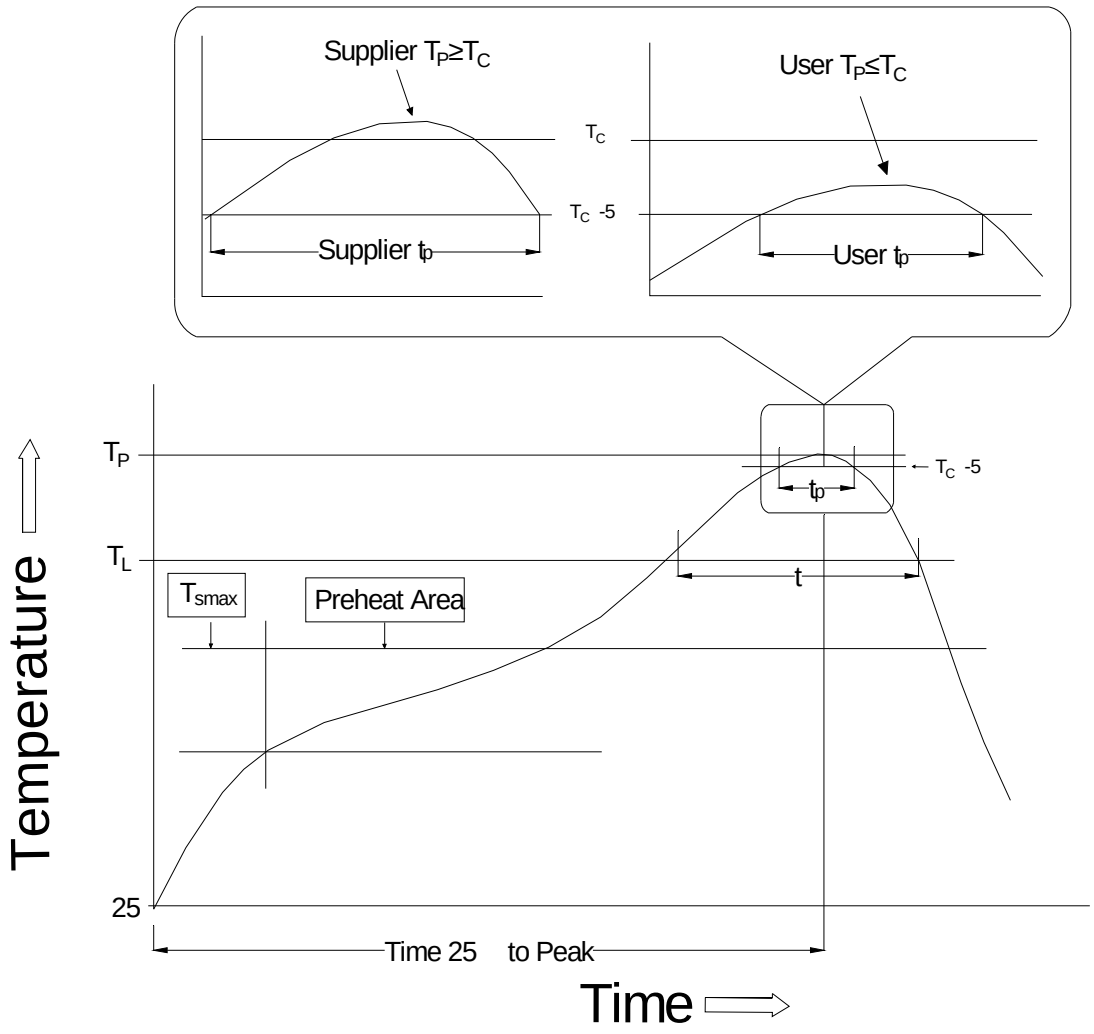
Ref.	Dimensions					
	Millimeters			Inches		
	Min.	Typ.	Max.	Min.	Typ.	Max.
A	13.50		13.70	0.531		0.539
B	6.15		6.35	0.242		0.250
C	0.10		0.30	0.004		0.012
D	3.50		3.70	0.138		0.146
E	14.71		15.31	0.579		0.603
F	0.52		1.02	0.020		0.040
G	16.36		16.86	0.644		0.664
H	0.10		0.40	0.004		0.016
I	3.65		3.95	0.144		0.156
J	0.307		0.607	0.012		0.024
K	1.02		1.52	0.040		0.060

RECOMMENDED SOLDER MASK (Dimensions in mm unless otherwise stated)



CARRIER TAPE SPECIFICATIONS (Dimensions in mm unless otherwise stated)

REFLOW INFORMATION



Note:

1. Reflow soldering is recommended at the temperatures and times shown, no more than three times.

2. Avoid direct contact between the epoxy body and any tools or surfaces exceeding its maximum storage temperature.

3. Application of pressure on the epoxy body is prohibited at elevated temperatures. In specific scenarios, any applied force must not exceed 2.5N.

4. Ensure the component has cooled to ambient temperature before proceeding with any subsequent manufacturing steps.

5. The component has a shelf life of one year when stored under standard conditions.

6. Recommend storage Temp.: 0~40°C;

Recommend storage humidity: <60%;

MSL level: MSL 1